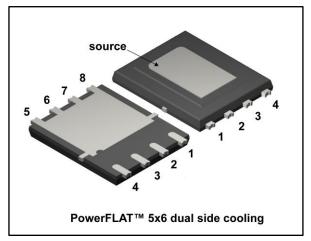


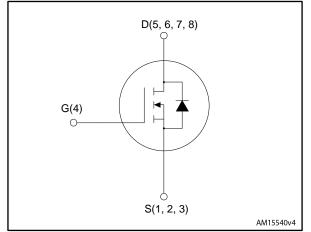
## STLD200N4F6AG

# Automotive-grade N-channel 40 V, 1.27 mΩ typ., 120 A STripFET™ F6 Power MOSFET in a PowerFLAT™ 5x6 DSC

Datasheet - production data



#### Figure 1: Internal schematic diagram



#### **Features**

Order code	VDS	RDS(on) max.	ΙD
STLD200N4F6AG	40 V	1.50 mΩ	120 A

- AEC-Q101 qualified
- Very low on-resistance
- Very low gate charge
- High avalanche ruggedness
- Low gate drive power loss
- Wettable flank package

### **Applications**

• Switching applications

#### Description

This device is an N-channel Power MOSFET developed using the STripFET<sup>TM</sup> F6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R<sub>DS(on)</sub> in all packages.

#### Table 1: Device summary

Order code	Marking	Package	Packaging
STLD200N4F6AG	200	PowerFLAT™ 5x6 dual side cooling	Tape and reel

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This is information on a product in full production.

#### Contents

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### 1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit	
VDS	Drain-source voltage	40	V	
V <sub>GS</sub>	Gate-source voltage	±20	V	
I <sub>D</sub> <sup>(1)(2)</sup>	Drain current (continuous) at T <sub>C</sub> = 25 °C	120	А	
ID <sup>(1)(2)</sup>	Drain current (continuous) at T <sub>C</sub> = 100 °C	120	А	
I <sub>DM</sub> <sup>(2)(3)</sup>	Drain current (pulsed)	480	А	
Ртот <sup>(2)</sup>	Total dissipation at $T_c = 25 \ ^{\circ}C$	158	W	
TJ	T <sub>J</sub> Operating junction temperature range		°C	
T <sub>stg</sub>	Storage temperature range	-55 to 175 °(		

#### Notes:

<sup>(1)</sup>Limited by package

 $^{(2)}\mbox{The value is rated according to $R$thj-case bottom side.}$ 

<sup>(3)</sup>Pulse width limited by safe operating area

#### Table 3: Thermal data

Symbol	Parameter	Value	Unit
Rthj-c top side	Thermal resistance junction-case top side	2.90	
Rthj-c bottom side	Thermal resistance junction-case bottom side	0.95	°C/W
Rthj-pcb <sup>(1)</sup>	Thermal resistance junction-pcb	31.3	

#### Notes:

<sup>(1)</sup>When mounted on 1 inch<sup>2</sup> 2 Oz. Cu board, t  $\leq$  10 s

#### Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I <sub>AV</sub>	Avalanche current, repetitive or not repetitive (pulse width limited by maximum junction temperature)	90	А
E <sub>AS</sub>	Single pulse avalanche energy (T <sub>j</sub> = 25 °C, $I_C = I_{AV}$ , $V_{DD} = 16$ V)	400	mJ



### 2 Electrical characteristics

(Tc= 25 °C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)DSS</sub>	Drain-source breakdown voltage	$V_{GS}$ = 0 V, $I_D$ = 1 mA	40			V
	Zara gata valtaga drain	$V_{GS}$ = 0 V, $V_{DS}$ = 16 V			1	μΑ
I <sub>DSS</sub> Zero gate voltage drain current	$V_{GS} = 0 V, V_{DS} = 16 V,$ Tj = 125 °C <sup>(1)</sup>			10	μA	
I <sub>GSS</sub>	Gate-body leakage current	$V_{DS}$ = 0 V, $V_{GS}$ = ±20 V			±100	nA
V <sub>GS(th)</sub>	Gate threshold voltage	$V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $\mu$ A	2.5		3.5	V
Static drain-source		$V_{GS}$ = 10 V, $I_{D}$ = 75 A		1.27	1.50	mΩ
R <sub>DS(on)</sub>	on-resistance	$V_{GS} = 6.5 \text{ V}, I_D = 75 \text{ A}$		1.48	2.00	11122

#### Notes:

<sup>(1)</sup>Defined by design, not subject to production test.

Symbol	Parameter Test conditions		Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	10700	-	pF
Coss	Output capacitance	V <sub>DS</sub> = 10 V, f = 1 MHz,	-	1530	-	pF
Crss	Reverse transfer capacitance	$V_{GS} = 0 V$	-	1100	-	pF
Qg	Total gate charge	$V_{DD} = 32 \text{ V}, \text{ I}_{D} = 90 \text{ A}, \text{ V}_{GS} = 0$	-	172	-	nC
Qgs	Gate-source charge	to 10 V (see Figure 14: "Test circuit for gate charge	-	56	-	nC
Q <sub>gd</sub>	Gate-drain charge	behavior")	-	48	-	nC

#### Table 6: Dynamic

#### Table 7: Switching times

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
t <sub>d(on)</sub>	Turn-on delay time	V <sub>DD</sub> = 30 V, I <sub>D</sub> = 75 A	-	150	-	ns
tr	Rise time	$R_G = 30 \Omega$ , $V_{GS} = 10 V$ (see Figure 13: "Test circuit for	-	440	-	ns
t <sub>d(off)</sub>	Turn-off-delay time	resistive load switching times"	-	600	-	ns
t <sub>f</sub>	Fall time	and Figure 18: "Switching time waveform")	-	410	-	ns

#### Electrical characteristics

	Table 8: Source drain diode						
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
I <sub>SD</sub> <sup>(1)</sup>	Source-drain current		-		120	А	
I <sub>SDM</sub> <sup>(1)(2)</sup>	Source-drain current (pulsed)	urrent			480	А	
V <sub>SD</sub> <sup>(3)</sup>	Forward on voltage	$V_{GS} = 0 V, I_{SD} = 90 A$	-		1.2	V	
trr	Reverse recovery time	I <sub>SD</sub> = 90 A, di/dt = 100 A/µs,		40		ns	
Qrr	Reverse recovery charge	V <sub>DD</sub> = 20 V (see Figure 15: "Test circuit for inductive load	-	53		nC	
I <sub>RRM</sub>	Reverse recovery current	switching and diode recovery times")	-	2.5		А	

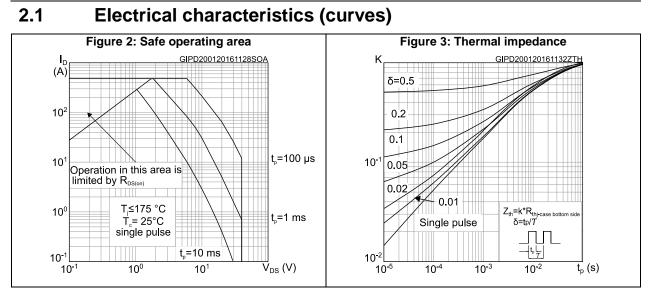
#### Notes:

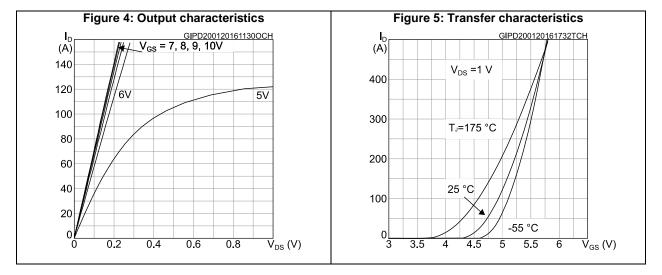
<sup>(1)</sup>Limited by package.

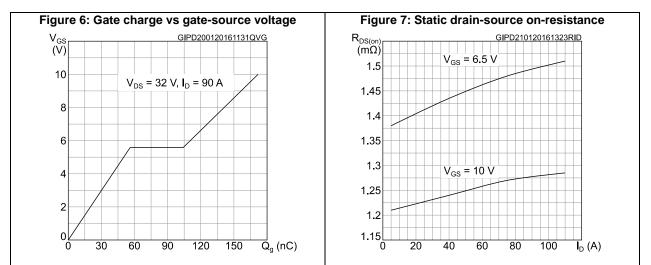
 $^{(2)}\mbox{Pulse}$  width is limited by safe operating area.

 $^{(3)}\text{Pulse test:}$  pulse duration = 300  $\mu\text{s},$  duty cycle 1.5%







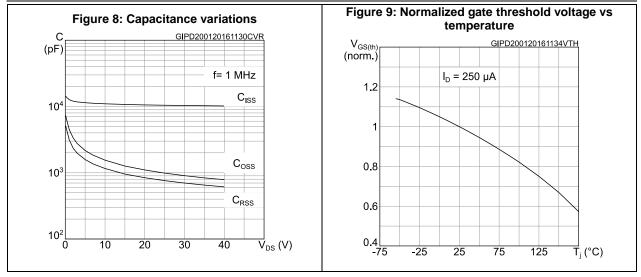


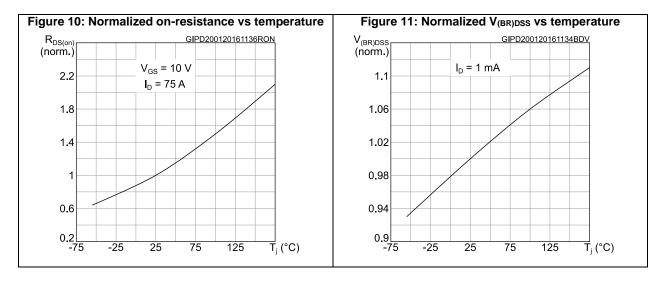


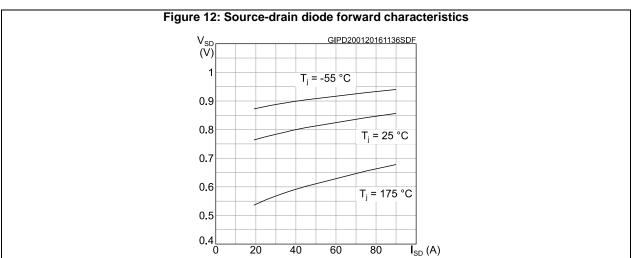
#### STLD200N4F6AG

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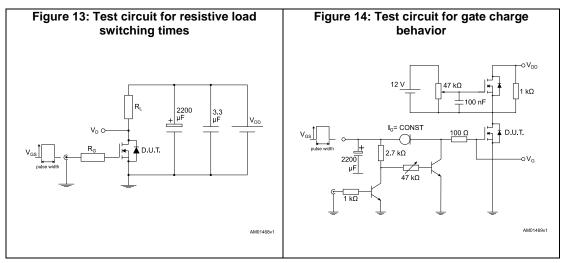
#### **Electrical characteristics**

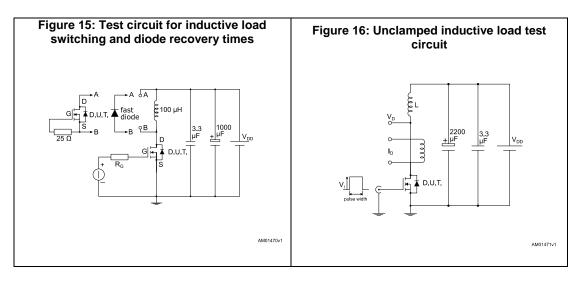


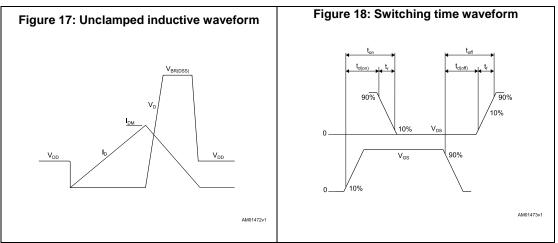




### 3 Test circuits







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### 4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK<sup>®</sup> is an ST trademark.

### 4.1 PowerFLAT<sup>™</sup> 5x6 dual side cooling package information

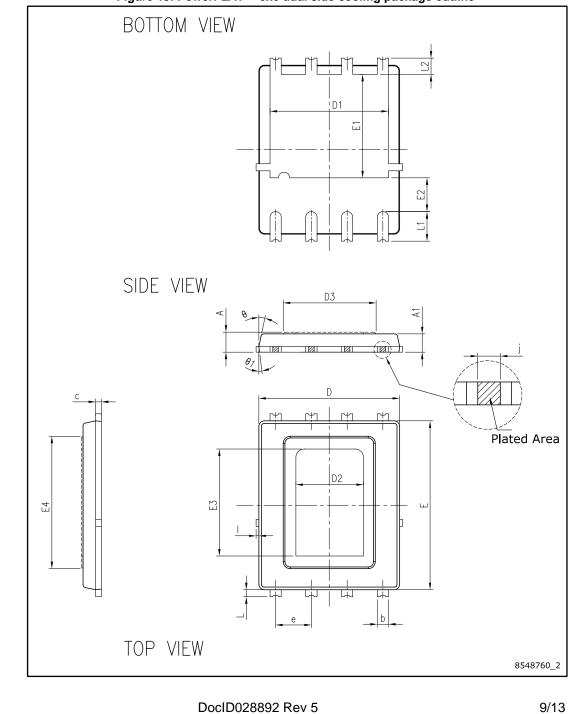


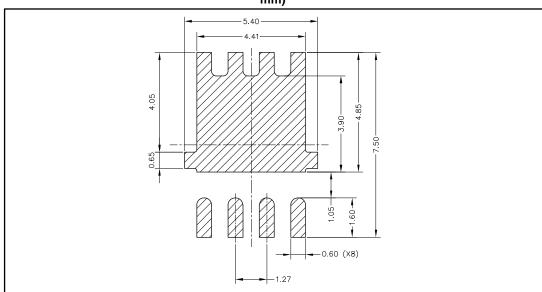
Figure 19: PowerFLAT™ 5x6 dual side cooling package outline

#### Package information

STLD200N4F6AG

Table 9: PowerFLAT™ 5x6 dual side cooling mechanical data					
Dim		mm			
Dim.	Min.	Тур.	Max.		
A	0.66	0.71	0.76		
A1	0.60		0.75		
b	0.33	0.43	0.53		
С	0.15	0.203	0.30		
D		5.00 BSC			
D1	4.06	4.21	4.36		
D2		2.40 BSC			
D3	2.80	3.30	3.80		
E		6.00 BSC			
E1	3.525	3.675	3.825		
E2	1.05	1.20	1.35		
E3		3.80 BSC			
E4	4.20	4.70	5.20		
е		1.27 BSC			
I			0.15		
L	0.15	0.25	0.35		
L1	0.925	1.05	1.175		
L2	0.45	0.575	0.70		
θ		12° BSC			
<del>.</del> 91		7° BSC			
j		0.20 BSC			

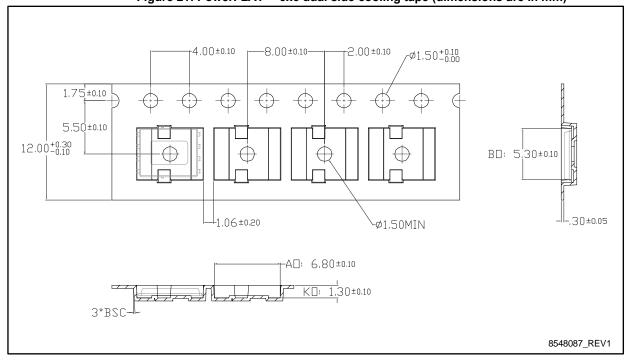
Figure 20: PowerFLAT™ 5x6 dual side cooling recommended footprint (dimensions are in mm)



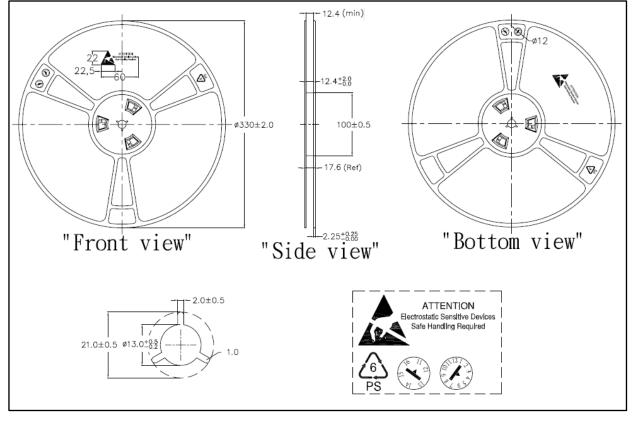


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### 4.2 PowerFLAT<sup>™</sup> 5x6 dual side cooling packing information Figure 21: PowerFLAT<sup>™</sup> 5x6 dual side cooling tape (dimensions are in mm)







### 5 Revision history

Table 10: Document revision history

Date	Revision	Changes
19-Jan-2016	1	First release
07-Feb-2017	2	Document status promoted from preliminary to production data. Updated <i>Table 3: "Thermal data"</i> and <i>Table 5: "On/off states"</i> . Minor text changes
23-Feb-2017	3	Updated features on cover page. Updated Table 5: "On/off states" and Figure 9: "Normalized gate threshold voltage vs temperature" Minor text changes
04-Apr-2017	4	Updated test conditions in Table 7: "Switching times".
12-Jul-2017 5 Added Section 4.2: "PowerFL information".		Added Section 4.2: "PowerFLAT™ 5x6 dual side cooling packing information".



#### STLD200N4F6AG

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